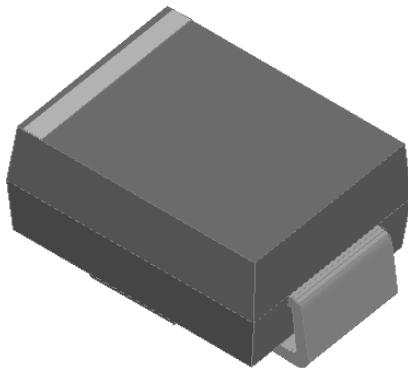
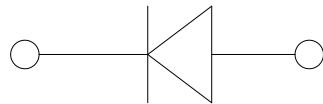


## Surface Mount Schottky Rectifier



SMB



### Features

- Low profile package
- Ideal for automated placement
- Guardring for overvoltage protection
- Low power losses, high efficiency
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

### Typical Applications

For use in low voltage high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

### Mechanical Data

- **Package:** DO-214AA (SMB)  
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

### ■ Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	SS52	SS53	SS54	SS55	SS56	SS58	SS510	SS515	SS520
Device marking code			SS52	SS53	SS54	SS55	SS56	SS58	SS510	SS515	SS520
Repetitive peak reverse voltage	VRRM	V	20	30	40	50	60	80	100	150	200
Average rectified output current @60Hz sine wave, resistance load, Ta (FIG.1)	IO	A						5.0			
Surge(non-repetitive)forward current @60Hz half-sine wave, 1 cycle, Ta=25°C	IFSM	A						100			
Storage temperature	Tstg	°C						-55 ~ +150			
Junction temperature	T <sub>j</sub>	°C			-55~+125				-55 ~ +150		

### ■ Electrical Characteristics (Ta=25°C Unless otherwise specified)

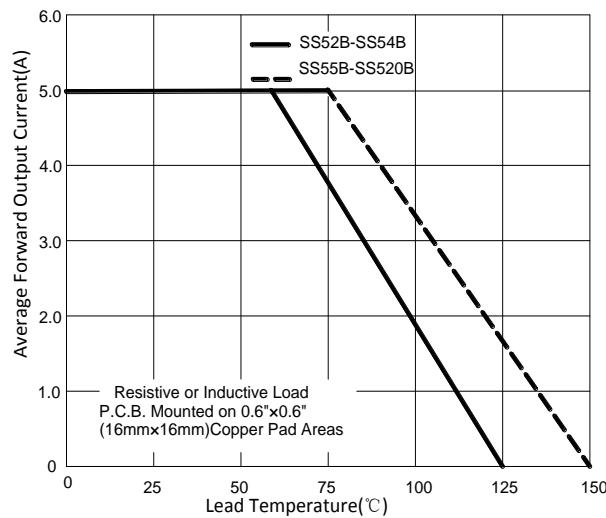
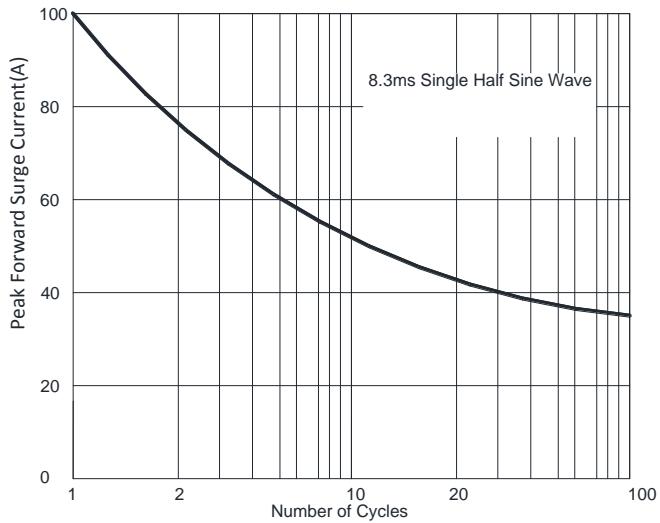
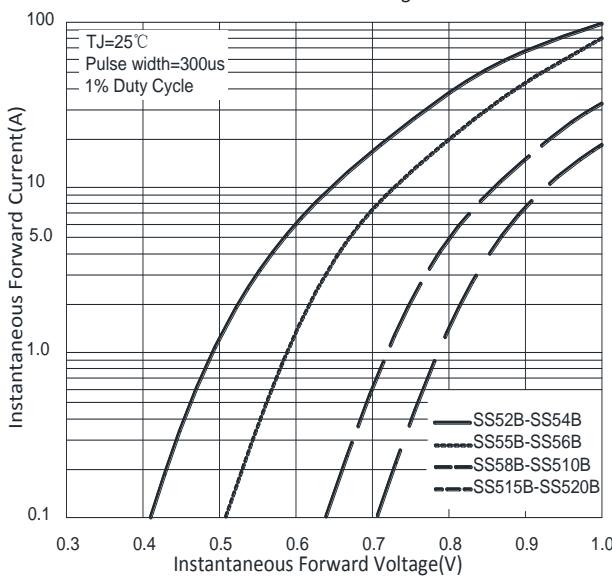
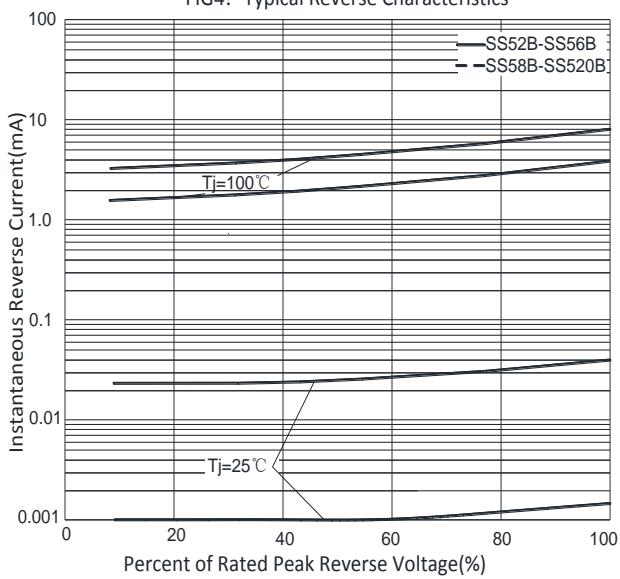
PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	SS52	SS53	SS54	SS55	SS56	SS58	SS510	SS515	SS520
Maximum instantaneous forward voltage drop per diode	V <sub>F</sub>	V	I <sub>FM</sub> =5.0A		0.60		0.70		0.85		0.90	
Maximum DC reverse current at rated DC blocking voltage per diode @ VRM=VRRM	IRRM	mA	Ta=25°C		0.5				0.1			
			Ta=100°C		10				5			

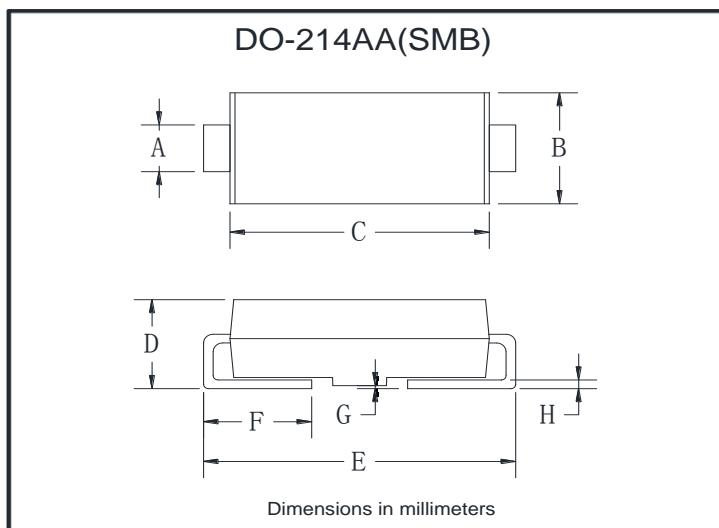
**■ Thermal Characteristics ( $T_a=25^\circ\text{C}$  Unless otherwise specified)**

PARAMETER	SYMBOL	UNIT	SS52	SS53	SS54	SS55	SS56	SS58	SS510	SS515	SS520
Thermal resistance	R <sub>θJ-A</sub> <sup>(1)</sup>	°C/W									58 <sup>1)</sup>
	R <sub>θJ-L</sub> <sup>(1)</sup>										20 <sup>1)</sup>

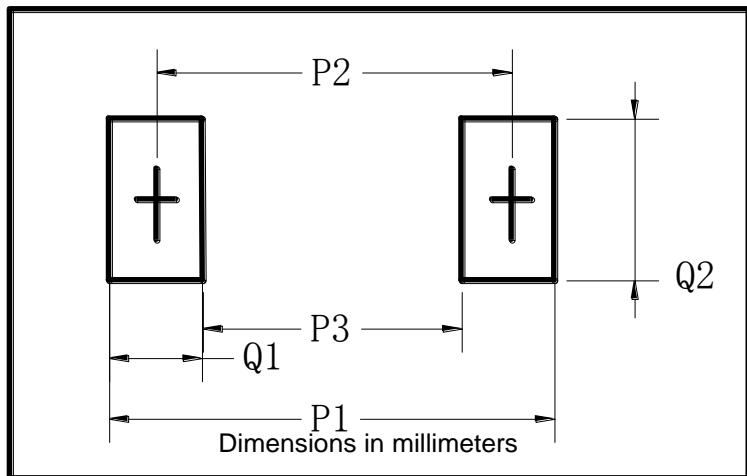
Note:

(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.6" x 0.6" (16 mm x 16 mm) copper pad areas

**■ Characteristics(Typical)**
**FIG1: Io-TL Curve**

**FIG2: Surge Forward Current Capability**

**FIG3: Forward Voltage**

**FIG4: Typical Reverse Characteristics**


**■ Outline Dimensions**

DO-214AA(SMB)		
Dim	Min	Max
A	1.85	2.15
B	3.30	3.94
C	4.25	4.75
D	1.99	2.61
E	5.21	5.59
F	0.90	1.41
G	0.10	0.20
H	0.15	0.31

**■ Suggested pad layout**

DO-214AA(SMB)	
Dim	Millimeters
P1	6.8
P2	4.3
P3	1.8
Q1	2.5
Q2	2.3